AMENDMENTS TO THE CLAIMS

Claim 1 (Currently Amended): A pressure sensor including

a semiconductor device capable of detecting ~~a pressure,~~ pressure;

a bonding wire;

a terminal that is connected to the semiconductor device by ~~a~~ the bonding ~~wire,~~ wire;

a housing having an accommodation space ~~for~~ accommodating the semiconductor device, the bonding wire and the ~~terminal,~~ terminal;

a diaphragm ~~for~~ sealing the accommodation ~~space,~~ space; and

a working fluid that is sealed in the accommodation ~~space,~~ space and transmits ~~the~~ pressure applied to the diaphragm to the semiconductor device, wherein

the working fluid is a silicone-based ~~oil,~~ oil; and

the terminal and the housing are sealed by a fluorine-based adhesive.

Claim 2 (Currently Amended): A pressure sensor including

a semiconductor device ~~that is~~ capable of ~~directly~~ detecting ~~a pressure,~~ pressure;

a bonding wire;

a terminal that is connected to the semiconductor device by ~~a~~ the bonding ~~wire,~~ wire; and

a housing having an accommodation space ~~for~~ accommodating the semiconductor device, the bonding wire and the terminal, wherein

the terminal and the housing are sealed by a fluorine-based adhesive.

Claim 3 (Original): The pressure sensor according to claim 1, wherein the fluorine-based adhesive is a perfluoro polyether resin composition.

Claim 4 (Original): The pressure sensor according to claim 2, wherein the fluorine-based adhesive is a perfluoro polyether resin composition.

Claim 5 (New): The pressure sensor according to claim 2, wherein the pressure sensor does not include a working fluid.

Claim 6 (New): A method of making a pressure sensor including a semiconductor device capable of detecting pressure; a bonding wire; a terminal that is connected to the semiconductor device by the bonding wire; a housing having an accommodation space accommodating the semiconductor device, the bonding wire and the terminal; a diaphragm sealing the accommodation space; and a working fluid that is sealed in the accommodation space and transmits pressure applied to the diaphragm to the semiconductor device, where the working fluid is a silicone-based oil; and the terminal and the housing are sealed by a fluorine-based adhesive, the method comprising

sealing the terminal and the housing with the fluorine-base adhesive; and

producing the pressure sensor of claim 1.

Claim 7 (New): A method of making a pressure sensor including a semiconductor device capable of detecting pressure; a bonding wire; a terminal that is connected to the semiconductor device by the bonding wire; and a housing having an accommodation space accommodating the semiconductor device, the bonding wire and the terminal, where the terminal and the housing are sealed by a fluorine-based adhesive, the method comprising

sealing the terminal and the housing with the fluorine-based adhesive; and

producing the pressure sensor of claim 2.